DIFE			Docket Number (Optional) FIS920030085US1		Application Number 10/605,857					
	INFO	RATION DISCLOSURE			Applicant(s) Michael P. Belyan		10/	005,057		
Filing Date Group Art				Group Art Unit						
					October 31, 2003					
U.S. PATENT DOCUMENTS										
*EXAMINER - INITIAL	REF	DOCUMENT NUMBER	DATE		NAME	CLASS	SUBCLASS	FILING IF APPRO		
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					11/10/04					
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							ugh citation if not	in conforms	ince and	

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

HDP PROCESS FOR HIGH ASPECT RATIO GAP FILLING

Application Number:

Confirmation Number:

First Named Applicant:

Michael Belyansky

Attorney Docket Number:

FIS920030085

Art Unit:

Examiner:

Search string:

(6211040 or 6395450 or 6514837 or 6531377 or 20030003244 or 20030013270 or

20030013271 or 20030050724).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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21	4	6531377	2003-03-11	Knorr et al.			

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
W	1	20030003244	2003-01-02	Rossman			•
21	2	20030013270	2003-01-16	Seitz			
4	3	20030013271	2003-01-16	Knorr et al.			
W	4	20030050724	2003-03-13	M'Saad et at.			

Signature

Examiner Name	Date
Rechar	11/10/0.4